



SSC8L48PN6

N-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
40V	$\pm 20V$	0.69m Ω @10V	245A
		1m Ω @4V5	

➤ Description

This device is N-Channel enhancement MOSFET. Uses SGT technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + ΔV_{DS} + R_g Tested!

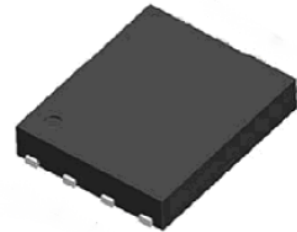
➤ Applications

- Load Switch
- PWM Application
- Power Management
- DC-DC Conversion

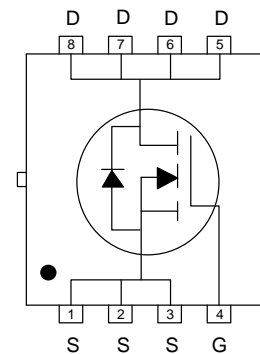
➤ Ordering Information

Device	Package	Shipping
SSC8L48PN6	PDFN5X6-8L	5000/Reel

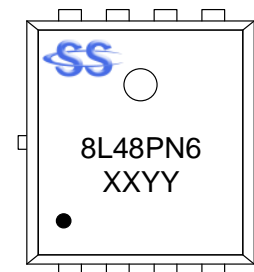
➤ Pin configuration



PDFN5X6-8L



Pin Configuration (Top View)



Marking

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		Ratings	Unit
V_{DSS}	Drain-to-Source Voltage		40	V
V_{GSS}	Gate-to-Source Voltage		± 20	V
I_{D}	Continuous Drain Current ^d	$T_{\text{C}}=25^{\circ}\text{C}$	245	A
		$T_{\text{C}}=100^{\circ}\text{C}$	140	
I_{DSM}	Continuous Drain Current ^a	$T_{\text{A}}=25^{\circ}\text{C}$	50	A
		$T_{\text{A}}=70^{\circ}\text{C}$	36	
I_{DM}	Pulsed Drain Current ^b		980	A
P_{D}	Power Dissipation ^c	$T_{\text{C}}=25^{\circ}\text{C}$	83.3	W
		$T_{\text{C}}=100^{\circ}\text{C}$	33.3	
P_{DSM}	Power Dissipation ^a	$T_{\text{A}}=25^{\circ}\text{C}$	3.13	W
		$T_{\text{A}}=70^{\circ}\text{C}$	2	
I_{AS}	Avalanche Current ^b $L=0.5\text{mH}$ Single Pulse		61	A
E_{AS}	Avalanche Energy ^b $L=0.5\text{mH}$ Single Pulse		930	mJ
T_{J}	Operation junction temperature		-55~150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range		-55~150	

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Max.	Unit
$R_{\theta\text{JA}}$	Junction-to-Ambient Thermal Resistance ^a	40	$^{\circ}\text{C}/\text{W}$
$R_{\theta\text{JC}}$	Junction-to-Case Thermal Resistance	1.5	

Note:

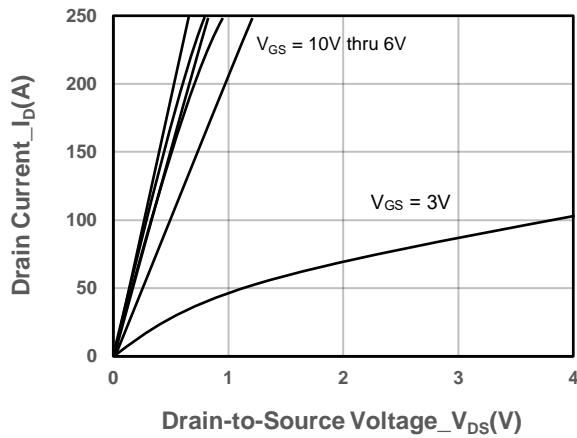
- The value of $R_{\theta\text{JA}}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_{\text{A}}=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_{D} is based on $T_{\text{J(MAX)}}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

➤ **Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

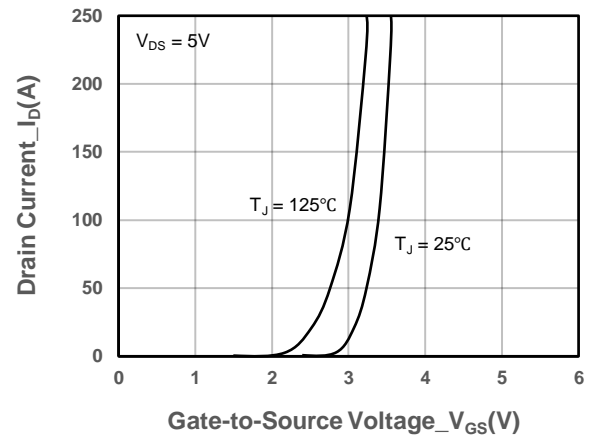
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	2	3	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 30A$		0.69	0.9	m Ω
		$V_{GS} = 4.5V, I_D = 15A$		1	1.4	m Ω
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 40V, V_{GS} = 0V$			1	μA
Gate-Source Leak Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = 15A$		0.78	1.4	V
Gate Resistance	R_G	$V_{DS} = 0V, f = 1MHz$		1.5		Ω
Input Capacitance	C_{ISS}	$V_{DS} = 20V, V_{GS} = 0V,$ $f = 1MHz$		7450		pF
Output Capacitance	C_{OSS}			1340		
Reverse Transfer Capacitance	C_{RSS}			490		
Total Gate Charge	Q_G	$V_{GS} = 10V, V_{DS} = 20V,$ $I_D = 20A$		85		nC
Gate to Source Charge	Q_{GS}			25		
Gate to Drain Charge	Q_{GD}			16		
Turn-on Delay Time	$T_{D(ON)}$	$V_{GS} = 10V, V_{DS} = 20V,$ $R_L = 2\Omega, R_G = 3\Omega$		16		ns
Rise Time	T_r			90		
Turn-off Delay Time	$T_{D(OFF)}$			150		
Fall Time	T_f			80		
Diode Recovery Time	T_{rr}	$I_F = 20A, di/dt = 100A/\mu s$		50		ns
Diode Recovery Charge	Q_{rr}	$I_F = 20A, di/dt = 100A/\mu s$		80		nC



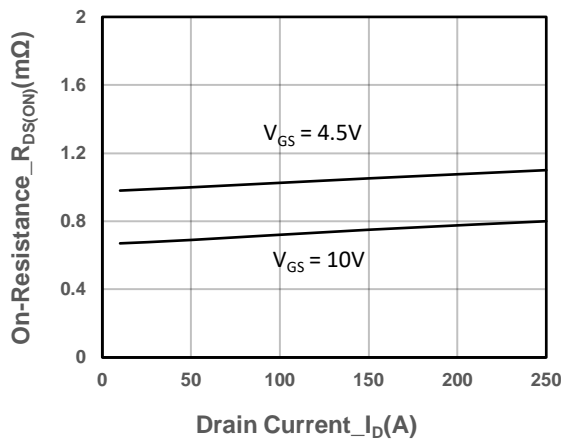
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



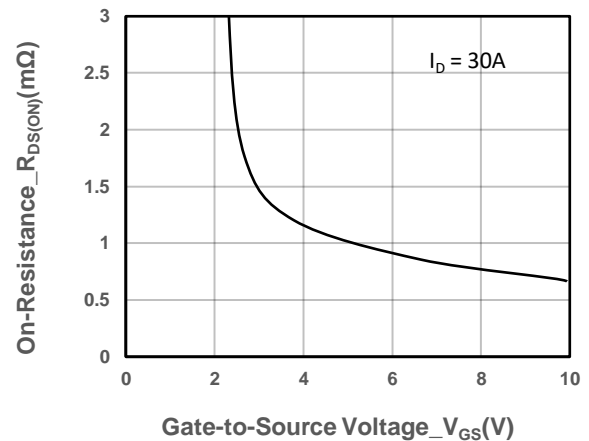
Output Characteristics



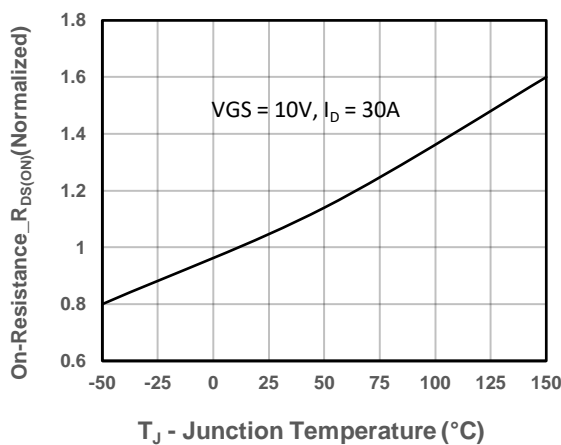
Transfer Characteristics



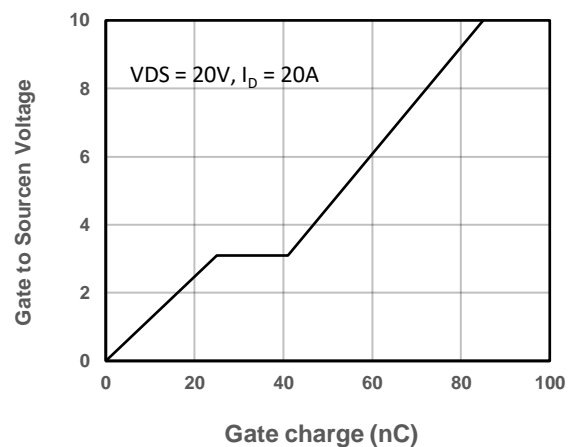
On-Resistance vs. Drain Current and Gate Voltage



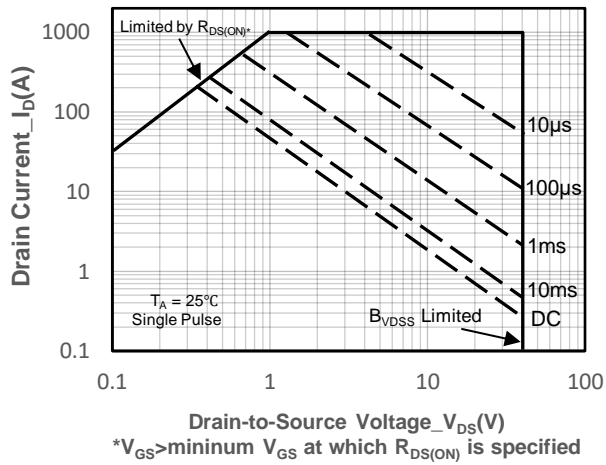
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature

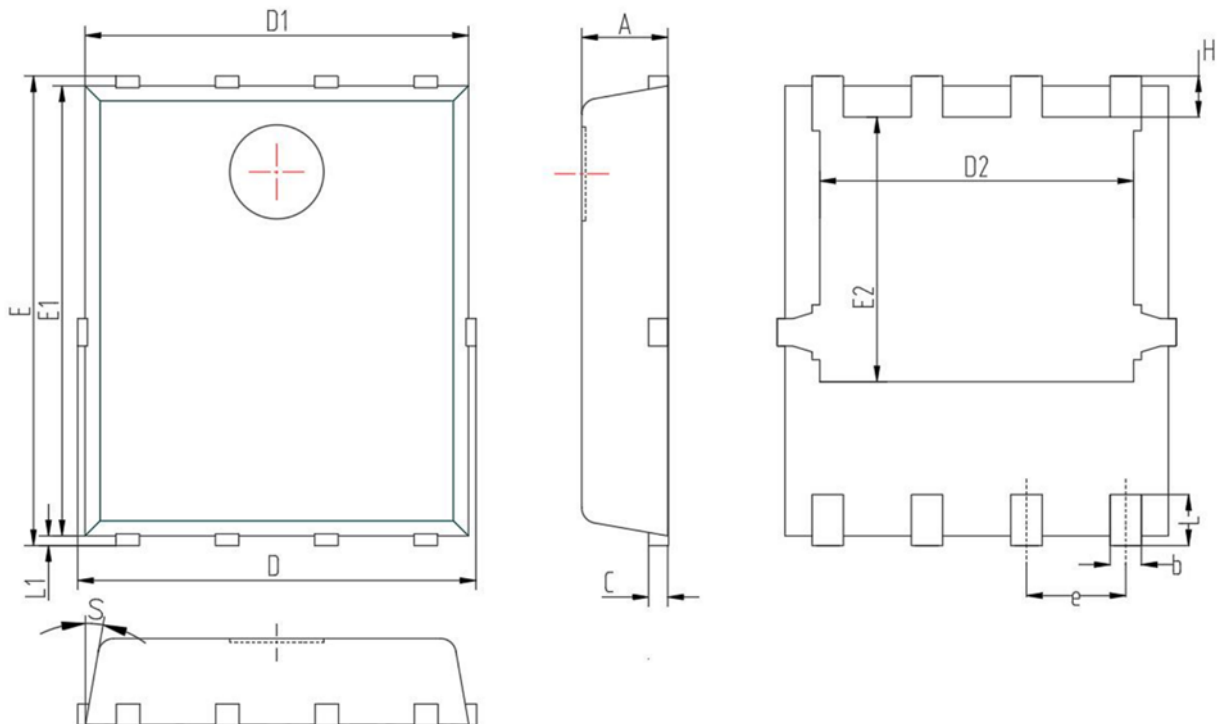


Gate-Source Voltage vs. Gate charge



Safe Operating Area vs. Junction-to-Ambient

➤ Package Information



Symbol	MILL IMETER		
	Min	Nom	Max
A	0.90	1.05	1.20
b	0.25	0.30	0.51
c	0.15	0.25	0.35
D	4.80	5.10	5.40
D1	4.80	5.00	5.20
D2	3.70	4.00	4.30
E	5.80	6.15	6.50
E1	5.50	5.75	5.95
E2	3.30	3.45	3.67
e	1.27BSC		
H	0.40	0.60	0.93
L	0.45	0.65	0.85
L1	0.00	0.10	0.25
S	0°	--	12°



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